

| | |
|----------------------|---|
| Applications | Commercial Grade |
| Feature | <div style="border: 1px solid black; padding: 2px;">Multilayer</div> Multilayer <div style="border: 1px solid black; padding: 2px;">Non-Mag Core</div> Non-Magnetic Core (Dielectric Ceramic) <div style="border: 1px solid black; padding: 2px;">High Q</div> High Q |
| Series Type | MLG-P |
| Status | Production |
| Brand | TDK |



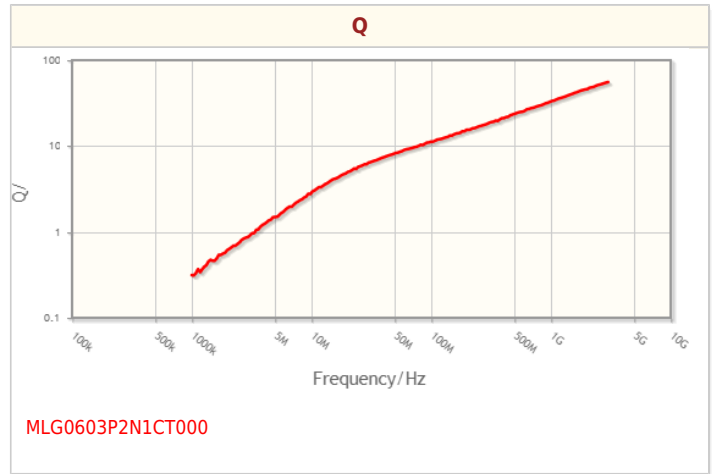
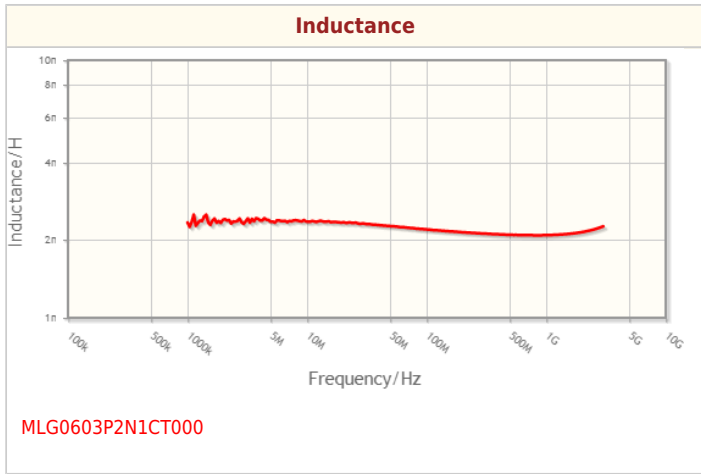
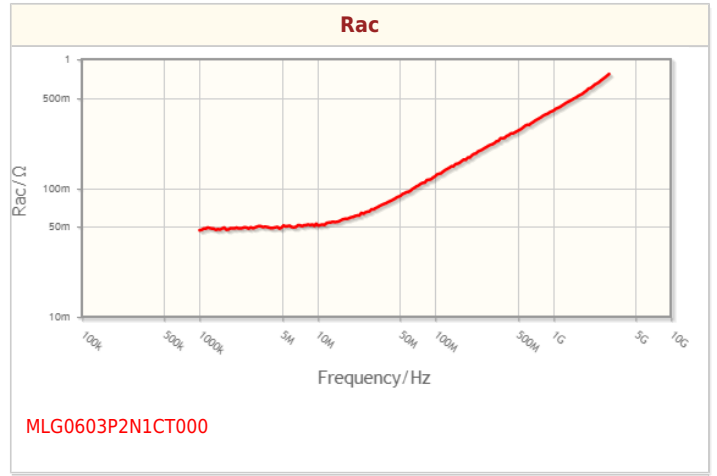
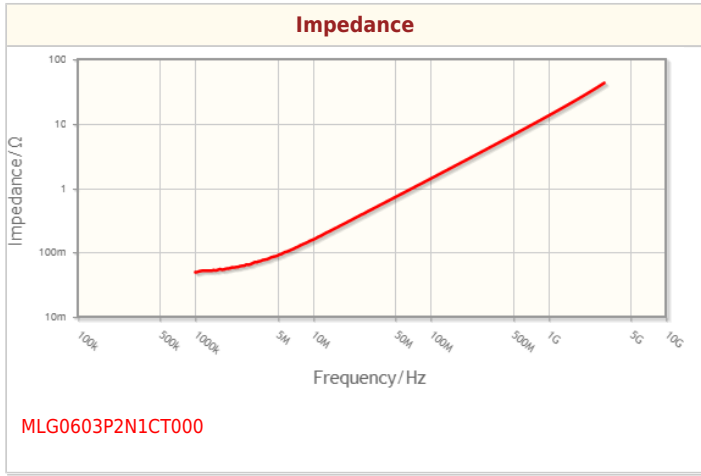
| Size | |
|------------------------------|----------------|
| Length(L) | 0.60mm ±0.03mm |
| Width(W) | 0.30mm ±0.03mm |
| Thickness Height | 0.30mm ±0.03mm |
| Recommended Land Pattern (A) | 0.25mm Nom. |
| Recommended Land Pattern (B) | 0.30mm Nom. |
| Recommended Land Pattern (C) | 0.30mm Nom. |

| Electrical Characteristics | |
|--------------------------------|------------------------|
| Inductance | 2.1nH ±0.2nH at 500MHz |
| Rated Current | 600mA |
| DC Resistance [Typ.] | 50mΩ |
| DC Resistance [Max.] | 100mΩ |
| Self Resonant Frequency [Min.] | 8GHz |
| Self Resonant Frequency [Typ.] | 9.8GHz |
| Q [Min.] | 14 at 500MHz |
| Q [Typ.] | 18 at 500MHz |

| Other | |
|---|--|
| Operating Temp. Range (Including Self-Temp. Rise) | -55 to 125°C |
| Soldering Method | Reflow |
| AEC-Q200 | NO |
| Packing | Punched (Paper)Taping [180mm Reel, Tape width 8mm] |
| Package Quantity | 15000pcs |
| Weight | 0.0002g |

! Images are for reference only and show exemplary products.
 ! This PDF document was created based on the data listed on the TDK Corporation website.
 ! All specifications are subject to change without notice.

Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)



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Associated Images

